Date: Sep.12,2014

RENESAS TECHNICAL UPDATE

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Renesas Electronics Corporation

Product Category	Standard Logic IC		Document No.	TN-SLG-A102A/E	Rev.	1.00
Title	The change of the Die-pad size of Leadframe.		Information Category	Technical Notification		
Applicable Product	Standard Logic IC DILP-14,DILP-16 Package products	Lot No. Since Feb, 2015	Reference Document	Nothing		

1. Content of change.

   The Leadframe specification of DILP-14 and DILP-16 is standardized.

   Although the pattern of an inner lead changes, a main change part is Die-pad size.

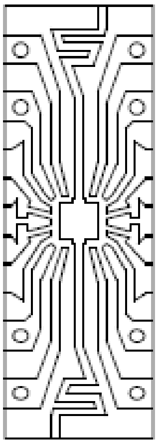
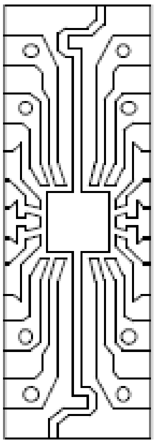
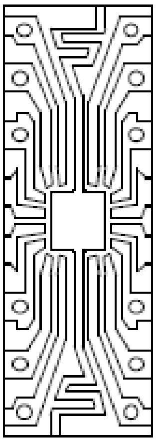
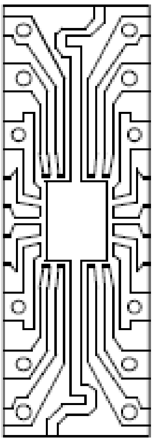
DILP-14		DILP-16	
Current	New	Current	New
 Die Pad Size 1.7mm × 1.7mm	 Die Pad Size 2.6mm × 2.6mm	 Die Pad Size 2.3mm × 2.5mm	 Die Pad Size 2.6mm × 3.4mm

Figure .1 Inner lead pattern current and new comparison.

2. The reason for change.

   For the stable supply of products.

3. Change start.

   This change is applied from the production in Feb.2015.

4. Product features etc..

   There is no change of the electrical specification and reliability, etc. by this change.

5. Applicable products.

DILP-14

- HD74AC08P, HD74AC32P, HD74AC164P, HD74AC00P
- HD74HC00P, HD74HC02P, HD74HC04P, HD74HC08P, HD74HC14P, HD74HC32P, HD74HC74P, HD74HC86P, HD74HC4066P
- HD74LS00P, HD74LS02P, HD74LS03P, HD74LS04P, HD74LS05P, HD74LS06P, HD74LS07P, HD74LS08P HD74LS10P, HD74LS14P, HD74LS20P, HD74LS32P, HD74LS38P, HD74LS74AP, HD74LS86P

DILP-16

- HD26C32AP, HD26C31P, HD74AC138P
- HD74HC138P, HD74HC147P, HD74HC161P, HD74HC174P, HD74HC175P, HD74HC238P, HD74HC4051P HD74HC4538P, HD74HC4052P
- HD26LS32P, HD74LS123P, HD74LS138P, HD74LS139P, HD74LS145P, HD74LS151P, HD74LS156P HD74LS157P, HD74LS194AP, HD74LS248P, HD74LS251P, HD74LS390P, HD74LS47P, HD74LS76AP